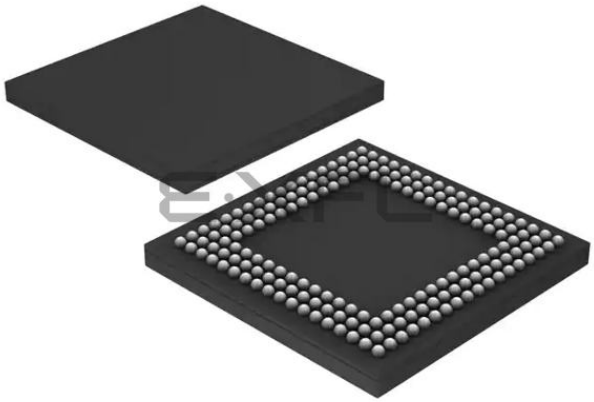


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, Microwire, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	118
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	264K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	180-TFBGA
Supplier Device Package	180-TFBGA (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc43s20fet180e

- Two SSP controllers with FIFO and multi-protocol support. Both SSPs with DMA support.
- One SPI controller.
- One Fast-mode Plus I^2C-bus interface with monitor mode and with open-drain I/O pins conforming to the full I^2C-bus specification. Supports data rates of up to 1 Mbit/s.
- One standard I^2C-bus interface with monitor mode and with standard I/O pins.
- Two I^2S interfaces, each with DMA support and with one input and one output.

- Digital peripherals
  - External Memory Controller (EMC) supporting external SRAM, ROM, NOR flash, and SDRAM devices.
  - LCD controller with DMA support and a programmable display resolution of up to 1024 H $\times$ 768 V. Supports monochrome and color STN panels and TFT color panels; supports 1/2/4/8 bpp Color Look-Up Table (CLUT) and 16/24-bit direct pixel mapping.
  - Secure Digital Input Output (SD/MMC) card interface.
  - Eight-channel General-Purpose DMA controller can access all memories on the AHB and all DMA-capable AHB slaves.
  - Up to 164 General-Purpose Input/Output (GPIO) pins with configurable pull-up/pull-down resistors.
  - GPIO registers are located on the AHB for fast access. GPIO ports have DMA support.
  - Up to eight GPIO pins can be selected from all GPIO pins as edge and level sensitive interrupt sources.
  - Two GPIO group interrupt modules enable an interrupt based on a programmable pattern of input states of a group of GPIO pins.
  - Four general-purpose timer/counters with capture and match capabilities.
  - One motor control Pulse Width Modulator (PWM) for three-phase motor control.
  - One Quadrature Encoder Interface (QEI).
  - Repetitive Interrupt timer (RI timer).
  - Windowed watchdog timer (WWDT).
  - Ultra-low power Real-Time Clock (RTC) on separate power domain with 256 bytes of battery powered backup registers.
  - Alarm timer; can be battery powered.
- Analog peripherals
  - One 10-bit DAC with DMA support and a data conversion rate of 400 kSamples/s.
  - Two 10-bit ADCs with DMA support and a data conversion rate of 400 kSamples/s. Up to eight input channels per ADC.
- Unique ID for each device.
- Power
  - Single 3.3 V (2.2 V to 3.6 V) power supply with on-chip internal voltage regulator for the core supply and the RTC power domain.
  - RTC power domain can be powered separately by a 3 V battery supply.
  - Four reduced power modes: Sleep, Deep-sleep, Power-down, and Deep power-down.
  - Processor wake-up from Sleep mode via wake-up interrupts from various peripherals.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P1_16	M7	L5	H9	64	[2]	N; PU	I/O	**GPIO0[3] —** General purpose digital input/output pin.
							I	**U2_RXD —** Receiver input for USART2.
							I/O	**SGPIO3 —** General purpose digital input/output pin.
							I	**ENET_CRS —** Ethernet Carrier Sense (MII interface).
							O	**T0_MAT0 —** Match output 0 of timer 0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_RX_DV —** Ethernet Receive Data Valid (RMII/MII interface).
P1_17	M8	L6	H10	66	[3]	N; PU	I/O	**GPIO0[12] —** General purpose digital input/output pin.
							I/O	**U2_UCLK —** Serial clock input/output for USART2 in synchronous mode.
							-	**R —** Function reserved.
							I/O	**ENET_MDIO —** Ethernet MIIM data input and output.
							I	**T0_CAP3 —** Capture input 3 of timer 0.
							O	**CAN1_TD —** CAN1 transmitter output.
							I/O	**SGPIO11 —** General purpose digital input/output pin.
							-	**R —** Function reserved.
P1_18	N12	N10	J10	67	[2]	N; PU	I/O	**GPIO0[13] —** General purpose digital input/output pin.
							I/O	**U2_DIR —** RS-485/EIA-485 output enable/direction control for USART2.
							-	**R —** Function reserved.
							O	**ENET_TXD0 —** Ethernet transmit data 0 (RMII/MII interface).
							O	**T0_MAT3 —** Match output 3 of timer 0.
							I	**CAN1_RD —** CAN1 receiver input.
							I/O	**SGPIO12 —** General purpose digital input/output pin.
							-	**R —** Function reserved.
P1_19	M11	N9	K9	68	[2]	N; PU	I	**ENET_TX_CLK (ENET_REF_CLK) —** Ethernet Transmit Clock (MII interface) or Ethernet Reference Clock (RMII interface).
							I/O	**SSP1_SCK —** Serial clock for SSP1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							O	**I2S0_RX_MCLK —** I2S receive master clock.
							I/O	**I2S1_TX_SCK —** Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I^2S-bus specification.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P2_5	K14	J12	D10	91	[3]	N; PU	I/O	**SGPIO14 —** General purpose digital input/output pin.
							I	**CTIN_2 —** SCTimer/PWM input 2. Capture input 2 of timer 0.
							I	**USB1_VBUS —** Monitors the presence of USB1 bus power. **Note:** This signal must be HIGH for USB reset to occur.
							I	**ADCTRIG1 —** ADC trigger input 1.
							I/O	**GPIO5[5] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							O	**T3_MAT2 —** Match output 2 of timer 3.
							O	**USB0_IND0 —** USB0 port indicator LED control output 0.
P2_6	K16	J14	G9	95	[2]	N; PU	I/O	**SGPIO7 —** General purpose digital input/output pin.
							I/O	**U0_DIR —** RS-485/EIA-485 output enable/direction control for USART0.
							I/O	**EMC_A10 —** External memory address line 10.
							O	**USB0_IND0 —** USB0 port indicator LED control output 0.
							I/O	**GPIO5[6] —** General purpose digital input/output pin.
							I	**CTIN_7 —** SCTimer/PWM input 7.
							I	**T3_CAP3 —** Capture input 3 of timer 3.
							-	**R —** Function reserved.
P2_7	H14	G12	C10	96	[2]	N; PU	I/O	**GPIO0[7] —** General purpose digital input/output pin. If this pin is pulled LOW at reset, the part enters ISP mode using USART0.
							O	**CTOUT_1 —** SCTimer/PWM output 1. Match output 3 of timer 3.
							I/O	**U3_UCLK —** Serial clock input/output for USART3 in synchronous mode.
							I/O	**EMC_A9 —** External memory address line 9.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**T3_MAT3 —** Match output 3 of timer 3.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P2_12	E15	D13	B9	106	[2]	N; PU	I/O	**GPIO1[12] —** General purpose digital input/output pin.
							O	**CTOUT_4 —** SCTimer/PWM output 4. Match output 3 of timer 3.
							-	**R —** Function reserved.
							I/O	**EMC_A3 —** External memory address line 3.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**U2_UCLK —** Serial clock input/output for USART2 in synchronous mode.
P2_13	C16	E14	A10	108	[2]	N; PU	I/O	**GPIO1[13] —** General purpose digital input/output pin.
							I	**CTIN_4 —** SCTimer/PWM input 4. Capture input 2 of timer 1.
							-	**R —** Function reserved.
							I/O	**EMC_A4 —** External memory address line 4.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**U2_DIR —** RS-485/EIA-485 output enable/direction control for USART2.
P3_0	F13	D12	A8	112	[2]	N; PU	I/O	**I2S0_RX_SCK —** I2S receive clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I^2S-bus specification*.
							O	**I2S0_RX_MCLK —** I2S receive master clock.
							I/O	**I2S0_TX_SCK —** Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I^2S-bus specification.
							O	**I2S0_TX_MCLK —** I2S transmit master clock.
							I/O	**SSP0_SCK —** Serial clock for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P3_4	A15	C14	B8	119	[2]	N; PU	I/O	**GPIO1[14] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SPIFI_SIO3 —** I/O lane 3 for SPIFI.
							O	**U1_TXD —** Transmitter output for UART 1.
							I/O	**I2S0_TX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							I/O	**I2S1_RX_SDA —** I2S1 Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*.
							O	**LCD_VD13 —** LCD data.
P3_5	C12	C11	B7	121	[2]	N; PU	I/O	**GPIO1[15] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SPIFI_SIO2 —** I/O lane 2 for SPIFI.
							I	**U1_RXD —** Receiver input for UART 1.
							I/O	**I2S0_TX_SDA —** I2S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*.
							I/O	**I2S1_RX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							O	**LCD_VD12 —** LCD data.
P3_6	B13	B12	C7	122	[2]	N; PU	I/O	**GPIO0[6] —** General purpose digital input/output pin.
							I/O	**SPI_MISO —** Master In Slave Out for SPI.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.
							I/O	**SPIFI_MISO —** Input 1 in SPIFI quad mode; SPIFI output IO1.
							-	**R —** Function reserved.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P3_7	C11	C10	D7	123	[2]	N; PU	-	**R —** Function reserved.
							I/O	**SPI_MOSI —** Master Out Slave In for SPI.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
							I/O	**SPIFI_MOSI —** Input I0 in SPIFI quad mode; SPIFI output IO0.
							I/O	**GPIO5[10] —** General purpose digital input/output pin.
							I/O	**SSP0_MOSI —** Master Out Slave in for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P9_6	L11	M9	-	72	[2]	N; PU	I/O	**GPIO4[11] —** General purpose digital input/output pin.
							O	**MCOB1 —** Motor control PWM channel 1, output B.
							I	**USB1_PWR_FAULT —** USB1 Port power fault signal indicating over-current condition; this signal monitors over-current on the USB1 bus (external circuitry required to detect over-current condition).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_COL —** Ethernet Collision detect (MII interface).
							I/O	**SGPIO8 —** General purpose digital input/output pin.
							I	**U0_RXD —** Receiver input for USART0.
PA_0	L12	L10	-	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**I2S1_RX_MCLK —** I2S1 receive master clock.
							O	**CGU_OUT1 —** CGU spare clock output 1.
							-	**R —** Function reserved.
PA_1	J14	H12	-	-	[3]	N; PU	I/O	**GPIO4[8] —** General purpose digital input/output pin.
							I	**QEI_IDX —** Quadrature Encoder Interface INDEX input.
							-	**R —** Function reserved.
							O	**U2_TXD —** Transmitter output for USART2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PA_2	K15	J13	-	-	[3]	N; PU	I/O	**GPIO4[9] —** General purpose digital input/output pin.
							I	**QEI_PHB —** Quadrature Encoder Interface PHB input.
							-	**R —** Function reserved.
							I	**U2_RXD —** Receiver input for USART2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PA_3	H11	E10	-	-	[3]	N; PU	I/O	**GPIO4[10] —** General purpose digital input/output pin.
							I	**QEI_PHA —** Quadrature Encoder Interface PHA input.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PA_4	G13	E12	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_9 —** SCTimer/PWM output 9. Match output 3 of timer 3.
							-	**R —** Function reserved.
							I/O	**EMC_A23 —** External memory address line 23.
							I/O	**GPIO5[19] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_0	B15	D14	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_10 —** SCTimer/PWM output 10. Match output 3 of timer 3.
							O	**LCD_VD23 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[20] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_1	A14	A13	-	-	[2]	N; PU	-	**R —** Function reserved.
							I	**USB1_ULPI_DIR —** ULPI link DIR signal. Controls the ULP data line direction.
							O	**LCD_VD22 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[21] —** General purpose digital input/output pin.
							O	**CTOUT_6 —** SCTimer/PWM output 6. Match output 2 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PC_7	G5	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D1 —** ULPI link bidirectional data line 1.
							-	**R —** Function reserved.
							I	**ENET_RXD3 —** Ethernet receive data 3 (MII interface).
							I/O	**GPIO6[6] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							O	**T3_MAT0 —** Match output 0 of timer 3.
							I/O	**SD_DAT3 —** SD/MMC data bus line 3.
PC_8	N4	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D0 —** ULPI link bidirectional data line 0.
							-	**R —** Function reserved.
							I	**ENET_RX_DV —** Ethernet Receive Data Valid (RMII/MII interface).
							I/O	**GPIO6[7] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							O	**T3_MAT1 —** Match output 1 of timer 3.
							I	**SD_CD —** SD/MMC card detect input.
PC_9	K2	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							I	**USB1_ULPI_NXT —** ULPI link NXT signal. Data flow control signal from the PHY.
							-	**R —** Function reserved.
							I	**ENET_RX_ER —** Ethernet receive error (MII interface).
							I/O	**GPIO6[8] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							O	**T3_MAT2 —** Match output 2 of timer 3.
							O	**SD_POW —** SD/MMC power monitor output.
PC_10	M5	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**USB1_ULPI_STP —** ULPI link STP signal. Asserted to end or interrupt transfers to the PHY.
							I	**U1_DSR —** Data Set Ready input for UART 1.
							-	**R —** Function reserved.
							I/O	**GPIO6[9] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							O	**T3_MAT3 —** Match output 3 of timer 3.
							I/O	**SD_CMD —** SD/MMC command signal.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PE_15	E13	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_0 —** SCTimer/PWM output 0. Match output 0 of timer 0.
							I/O	**I2C1_SCL —** I^2C1 clock input/output (this pin does not use a specialized I2C pad).
							O	**EMC_CKEOUT3 —** SDRAM clock enable 3.
							I/O	**GPIO7[15] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PF_0	D12	-	-	-	[2]	O; PU	I/O	**SSP0_SCK —** Serial clock for SSP0.
							I	**GP_CLKIN —** General-purpose clock input to the CGU.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**I2S1_TX_MCLK —** I2S1 transmit master clock.
PF_1	E11	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.
							-	**R —** Function reserved.
							I/O	**GPIO7[16] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I/O	**SGPIO0 —** General purpose digital input/output pin.
							-	**R —** Function reserved.
PF_2	D11	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**U3_TXD —** Transmitter output for USART3.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
							-	**R —** Function reserved.
							I/O	**GPIO7[17] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I/O	**SGPIO1 —** General purpose digital input/output pin.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
WAKEUP1	A10	C8	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration > 45 ns wakes up the part. This pin does not have an internal pull-up.
WAKEUP2	C9	E5	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration > 45 ns wakes up the part. This pin does not have an internal pull-up.
WAKEUP3	D8	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration > 45 ns wakes up the part. This pin does not have an internal pull-up.
ADC pins								
ADC0_0/ ADC1_0/DAC	E3	B6	A2	6	[8]	I; IA	I	ADC input channel 0. Shared between 10-bit ADC0/1 and DAC.
ADC0_1/ ADC1_1	C3	C4	A1	2	[8]	I; IA	I	ADC input channel 1. Shared between 10-bit ADC0/1.
ADC0_2/ ADC1_2	A4	B3	B3	143	[8]	I; IA	I	ADC input channel 2. Shared between 10-bit ADC0/1.
ADC0_3/ ADC1_3	B5	B4	A3	139	[8]	I; IA	I	ADC input channel 3. Shared between 10-bit ADC0/1.
ADC0_4/ ADC1_4	C6	A5	-	138	[8]	I; IA	I	ADC input channel 4. Shared between 10-bit ADC0/1.
ADC0_5/ ADC1_5	B3	C3	-	144	[8]	I; IA	I	ADC input channel 5. Shared between 10-bit ADC0/1.
ADC0_6/ ADC1_6	A5	A4	-	142	[8]	I; IA	I	ADC input channel 6. Shared between 10-bit ADC0/1.
ADC0_7/ ADC1_7	C5	B5	-	136	[8]	I; IA	I	ADC input channel 7. Shared between 10-bit ADC0/1.
RTC								
RTC_ALARM	A11	A10	C3	129	[11]	O	O	RTC controlled output. This pin has an internal pull-up. The reset state of this pin is LOW after POR. For all other types of reset, the reset state depends on the state of the RTC alarm interrupt.
RTCX1	A8	A8	A5	125	[8]	-	I	Input to the RTC 32 kHz ultra-low power oscillator circuit.
RTCX2	B8	B7	B5	126	[8]	-	O	Output from the RTC 32 kHz ultra-low power oscillator circuit.
Crystal oscillator pins								
XTAL1	D1	C1	B1	12	[8]	-	I	Input to the oscillator circuit and internal clock generator circuits.
XTAL2	E1	D1	C1	13	[8]	-	O	Output from the oscillator amplifier.
Power and ground pins								
USB0_VDDA 3V3_DRIVER	F3	E3	D1	16		-	-	Separate analog 3.3 V power supply for driver.

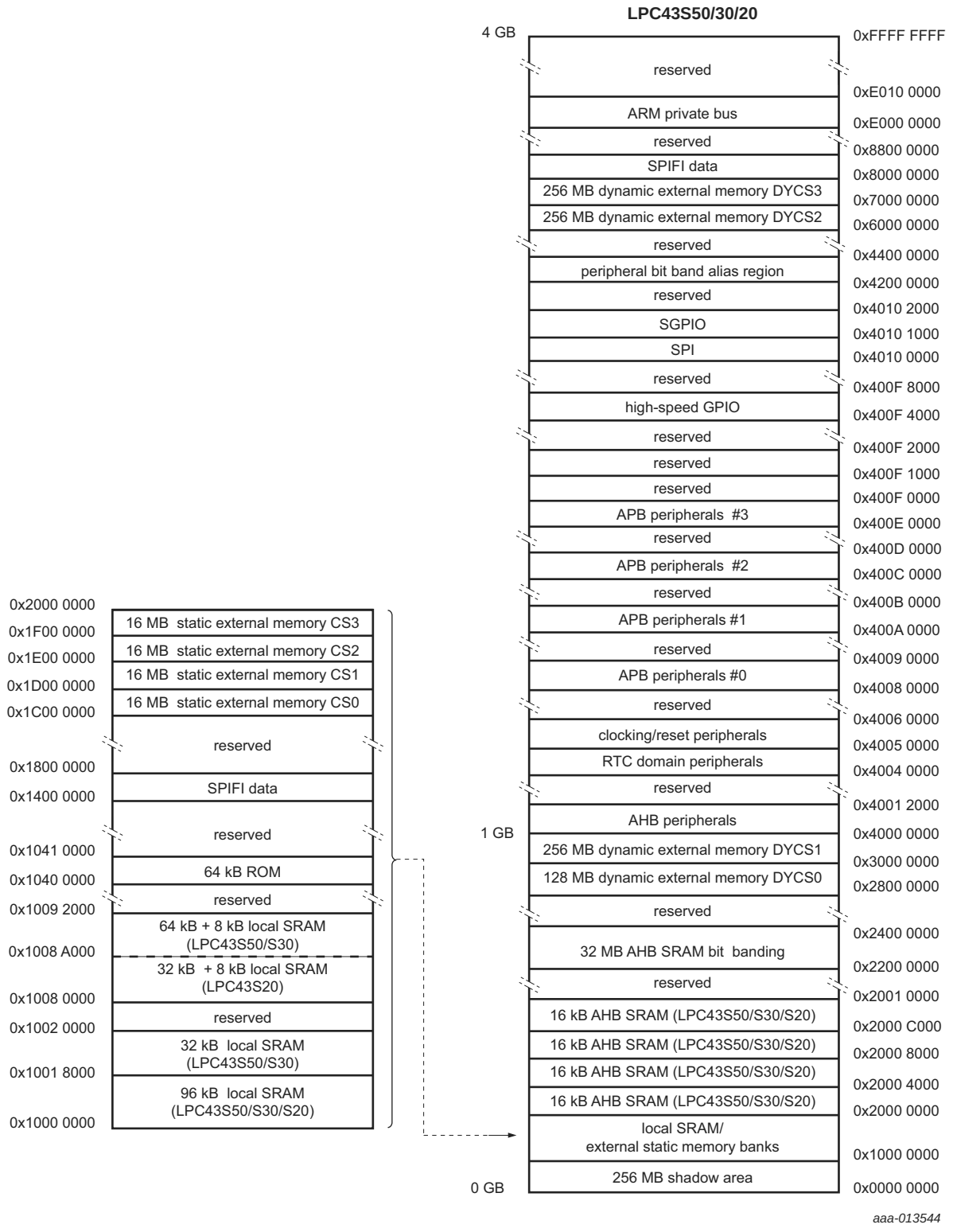


Fig 7. LPC43S50/S30/S20 Memory mapping (overview)

Table 10. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{LH}	HIGH-level leakage current	$V_I = V_{DD(IO)}$; on-chip pull-down resistor disabled		-	3	-	nA
		V_I = 5 V		-	-	20	nA
I_{OZ}	OFF-state output current	V_O = 0 V to $V_{DD(IO)}$; on-chip pull-up/down resistors disabled; absolute value		-	3	-	nA
V_I	input voltage	pin configured to provide a digital function;					
		$V_{DD(IO)} \geq$ 2.2 V		0	-	5.5	V
		$V_{DD(IO)}$ = 0 V		0	-	3.6	V
V_O	output voltage	output active		0	-	$V_{DD(IO)}$	V
V_{IH}	HIGH-level input voltage			0.7 × $V_{DD(IO)}$	-	5.5	V
V_{IL}	LOW-level input voltage			0	-	0.3 × $V_{DD(IO)}$	V
V_{hys}	hysteresis voltage			0.1 × $V_{DD(IO)}$	-	-	V
V_{OH}	HIGH-level output voltage	I_{OH} = −8 mA		$V_{DD(IO)}$ − 0.4	-	-	V
V_{OL}	LOW-level output voltage	I_{OL} = 8 mA		-	-	0.4	V
I_{OH}	HIGH-level output current	$V_{OH} = V_{DD(IO)}$ − 0.4 V		−8	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V		8	-	-	mA
I_{OHS}	HIGH-level short-circuit output current	drive HIGH; connected to ground	[12]	-	-	86	mA
I_{OLS}	LOW-level short-circuit output current	drive LOW; connected to $V_{DD(IO)}$	[12]	-	-	76	mA
I_{pd}	pull-down current	$V_I = V_{DD(IO)}$	[14][15][16]	-	62	-	µA
I_{pu}	pull-up current	V_I = 0 V	[14][15][16]	-	−62	-	µA
		$V_{DD(IO)} < V_I \leq$ 5 V		-	0	-	µA
Open-drain I^2C0-bus pins							
V_{IH}	HIGH-level input voltage			0.7 × $V_{DD(IO)}$	-	-	V
V_{IL}	LOW-level input voltage			0	0.14	0.3 × $V_{DD(IO)}$	V
V_{hys}	hysteresis voltage			0.1 × $V_{DD(IO)}$	-	-	V
V_{OL}	LOW-level output voltage	I_{OLS} = 3 mA		-	-	0.4	V

Table 10. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{LI}	input leakage current	$V_I = V_{DD(IO)}$	[13]	-	4.5	-	μA
		V_I = 5 V		-	-	10	μA
Oscillator pins							
$V_{i(XTAL1)}$	input voltage on pin XTAL1			−0.5	-	1.2	V
$V_{o(XTAL2)}$	output voltage on pin XTAL2			−0.5	-	1.2	V
C_{io}	input/output capacitance		[17]	-	-	0.8	pF
USB0 pins[18]							
V_I	input voltage	on pins USB0_DP; USB0_DM; USB0_VBUS					
		$V_{DD(IO)} \geq 2.2$ V		0	-	5.25	V
		$V_{DD(IO)}$ = 0 V		0	-	3.6	V
R_{pd}	pull-down resistance	on pin USB0_VBUS		48	64	80	kΩ
V_{IC}	common-mode input voltage	high-speed mode		−50	200	500	mV
		full-speed/low-speed mode		800	-	2500	mV
		chirp mode		−50	-	600	mV
$V_{i(dif)}$	differential input voltage			100	400	1100	mV
USB1 pins (USB1_DP/USB1_DM)[18]							
I_{OZ}	OFF-state output current	0 V < V_I < 3.3 V	[18]	-	-	±10	μA
V_{BUS}	bus supply voltage		[19]	-	-	5.25	V
V_{DI}	differential input sensitivity voltage	|(D+) − (D−)|		0.2	-	-	V
V_{CM}	differential common mode voltage range	includes V_{DI} range		0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage			0.8	-	2.0	V
V_{OL}	LOW-level output voltage for low-/full-speed	R_L of 1.5 kΩ to 3.6 V		-	-	0.18	V
V_{OH}	HIGH-level output voltage (driven) for low-/full-speed	R_L of 15 kΩ to GND		2.8	-	3.5	V
C_{trans}	transceiver capacitance	pin to GND		-	-	20	pF
Z_{DRV}	driver output impedance for driver which is not high-speed capable	with 33 Ω series resistor; steady state drive	[20]	36	-	44.1	Ω

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT}$ + 0.2 V. See Figure 18.

11.12 SPI interface

Table 25. Dynamic characteristics: SPI

T_{amb} = −40 °C to +85 °C; 2.2 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$T_{cy(PCLK)}$	PCLK cycle time			5			ns
$T_{cy(clk)}$	clock cycle time		[1]	40	-	-	ns
Master							
t_{DS}	data set-up time			7.2	-	-	ns
t_{DH}	data hold time			0	-	-	ns
$t_{v(Q)}$	data output valid time			-	-	3.7	ns
$t_{h(Q)}$	data output hold time			-	-	1.2	ns
Slave							
t_{DS}	data set-up time			1.2	-	-	ns
t_{DH}	data hold time			3 x $T_{cy(PCLK)}$ + 0.54	-	-	ns
$t_{v(Q)}$	data output valid time			-	-	3 x $T_{cy(PCLK)}$ + 9.7	ns
$t_{h(Q)}$	data output hold time			-	-	2 x $T_{cy(PCLK)}$ + 7.1	ns

[1] $T_{cy(clk)}$ = 8/BASE_SPI_CLK. Tcy(PCLK) = 1/BASE_SPI_CLK.

Table 27. Dynamic characteristics: Static asynchronous external memory interface *…continued*

C_L = 22 pF for EMC_Dn C_L = 20 pF for all others; T_{amb} = −40 °C to +85 °C; 2.2 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; values guaranteed by design. Timing parameters are given for single memory access cycles. In a normal read operation, the EMC changes the address while CS is asserted resulting in multiple memory accesses.

Symbol	Parameter[1]	Conditions		Min	Typ	Max	Unit
$t_{BLSHEOW}$	$\overline{BLS}$ HIGH to end of write time	PB = 0	[2] [5]	−1.9 + $T_{cy(clk)}$	-	−0.5 + $T_{cy(clk)}$	ns
$t_{BLSHDNV}$	$\overline{BLS}$ HIGH to data invalid time	PB = 0	[1] [2]	−2.5 + $T_{cy(clk)}$	-	1.4 + $T_{cy(clk)}$	ns
t_{CSHEOW}	$\overline{CS}$ HIGH to end of write time		[5]	−2.0	-	0	ns
$t_{BLSHDNV}$	$\overline{BLS}$ HIGH to data invalid time	PB = 1		−2.5	-	1.4	ns
t_{WEHANV}	WE HIGH to address invalid time	PB = 1		−0.9 + $T_{cy(clk)}$	-	2.4 + $T_{cy(clk)}$	ns

[1] Parameters specified for 40 % of $V_{DD(IO)}$ for rising edges and 60 % of $V_{DD(IO)}$ for falling edges.

[2] $T_{cy(clk)}$ = 1/CCLK (see LPC43xx User manual).

[3] End Of Read (EOR): longest of t_{CSHOEH}, t_{OEHANV}, $t_{CSHBLSH}$.

[4] Start Of Read (SOR): longest of t_{CSLAV}, t_{CSLOEL}, $t_{CSLBLSL}$.

[5] End Of Write (EOW): earliest of address not valid or $\overline{EMC\_BLSn}$ HIGH.

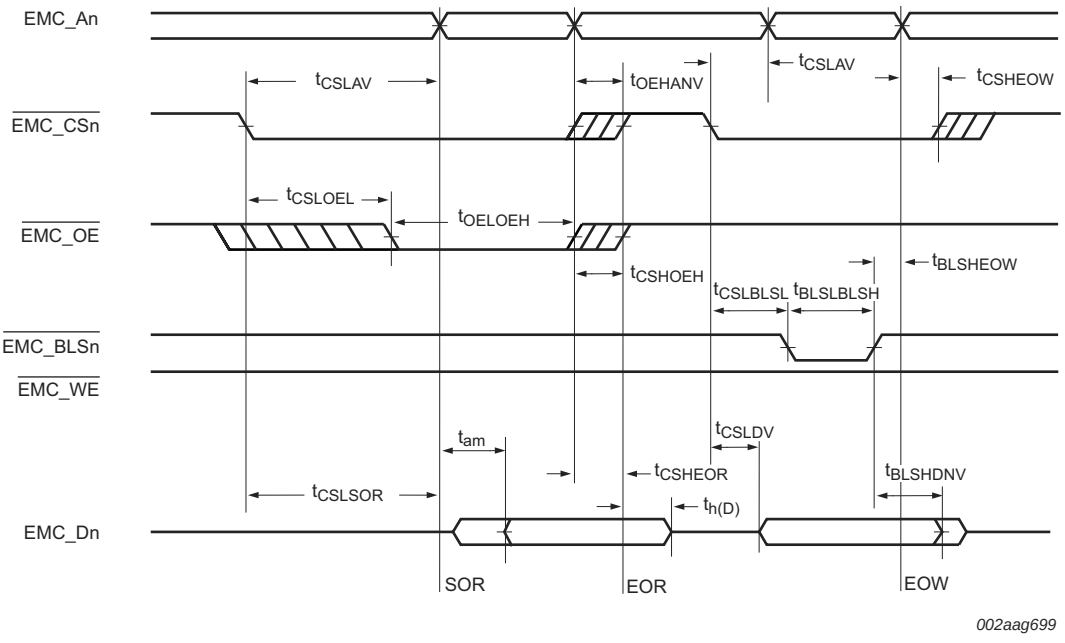


Fig 34. External static memory read/write access (PB = 0)

Table 32. Dynamic characteristics: Ethernet

T_{amb} = −40 °C to 85 °C; 2.2 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. Values guaranteed by design.

Symbol	Parameter	Conditions		Min	Max	Unit
RMII mode						
f_{clk}	clock frequency	for ENET_RX_CLK	[1]	-	50	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns
t_h	hold time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	2	-	ns
MII mode						
f_{clk}	clock frequency	for ENET_TX_CLK	[1]	-	25	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	[1][2]	4	-	ns
t_h	hold time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	[1][2]	2	-	ns
f_{clk}	clock frequency	for ENET_RX_CLK	[1]	-	25	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns
t_h	hold time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	2	-	ns

[1] Output drivers can drive a load ≥ 25 pF accommodating over 12 inch of PCB trace and the input capacitance of the receiving device.

[2] Timing values are given from the point at which the clock signal waveform crosses 1.4 V to the valid input or output level.

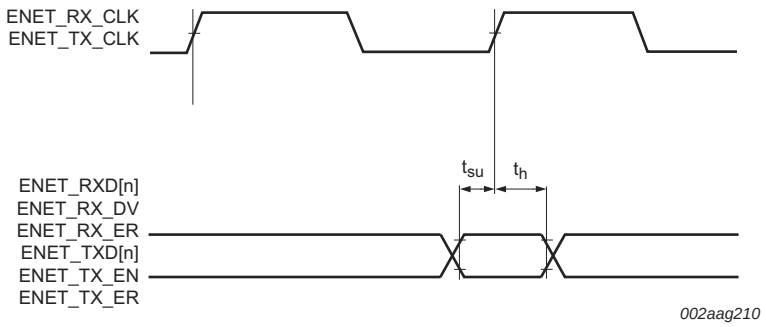


Fig 38. Ethernet timing

Table 40. LCD panel connections for TFT panels *…continued*

External pin	TFT 12 bit (4:4:4 mode)		TFT 16 bit (5:6:5 mode)		TFT 16 bit (1:5:5:5 mode)		TFT 24 bit	
	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function
LCD_VD0	-	-	-	-	-	-	P4_1	RED0
LCD_LP	P7_6	LCDLP	P7_6	LCDLP	P7_6	LCDLP	P7_6	LCDLP
LCD_ENAB /LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM
LCD_FP	P4_5	LCDFP	P4_5	LCDFP	P4_5	LCDFP	P4_5	LCDFP
LCD_DCLK	P4_7	LCDDCLK	P4_7	LCDDCLK	P4_7	LCDDCLK	P4_7	LCDDCLK
LCD_LE	P7_0	LCDLE	P7_0	LCDLE	P7_0	LCDLE	P7_0	LCDLE
LCD_PWR	P7_7	LCDPWR	P7_7	LCDPWR	P7_7	LCDPWR	P7_7	LCDPWR
GP_CLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN

13.2 Crystal oscillator

The crystal oscillator is controlled by the XTAL_OSC_CTRL register in the CGU (see *LPC43xx user manual*).

The crystal oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the PLL.

The oscillator can operate in one of two modes: slave mode and oscillation mode.

- In slave mode, couple the input clock signal with a capacitor of 100 pF (C_C in Figure 43), with an amplitude of at least 200 mV (RMS). The XTAL2 pin in this configuration can be left unconnected.
- External components and models used in oscillation mode are shown in Figure 44, and in Table 41 and Table 42. Since the feedback resistance is integrated on chip, only a crystal and the capacitances CX1 and CX2 need to be connected externally in case of fundamental mode oscillation L, CL and RS represent the fundamental frequency). The capacitance C_P in Figure 44 represents the parallel package capacitance and must not be larger than 7 pF. Parameters FC, CL, RS and CP are supplied by the crystal manufacturer.

Table 41. Recommended values for $C_{X1/X2}$ in oscillation mode (crystal and external components parameters) low frequency mode

Fundamental oscillation frequency	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
2 MHz	< 200 Ω	33 pF, 33 pF
	< 200 Ω	39 pF, 39 pF
	< 200 Ω	56 pF, 56 pF
4 MHz	< 200 Ω	18 pF, 18 pF
	< 200 Ω	39 pF, 39 pF
	< 200 Ω	56 pF, 56 pF
8 MHz	< 200 Ω	18 pF, 18 pF
	< 200 Ω	39 pF, 39 pF

13.3 RTC oscillator

In the RTC oscillator circuit, only the crystal (XTAL) and the capacitances C_{RTCX1} and C_{RTCX2} need to be connected externally. Typical capacitance values for C_{RTCX1} and C_{RTCX2} are $C_{RTCX1/2}$ = 20 (typical) $\pm$ 4 pF.

An external clock can be connected to RTCX1 if RTCX2 is left open. The recommended amplitude of the clock signal is $V_{i(RMS)}$ = 100 mV to 200 mV with a coupling capacitance of 5 pF to 10 pF. $V_{i(RMS)}$ must be lower than 450 mV. See Figure 43 for a similar slave-mode set-up that uses the crystal oscillator.

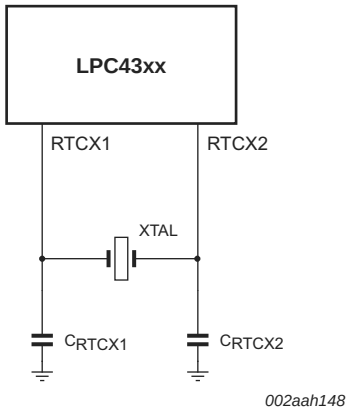


Fig 45. RTC 32 kHz oscillator circuit

13.4 XTAL and RTCX Printed Circuit Board (PCB) layout guidelines

Connect the crystal on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{x1}, C_{x2}, and C_{x3} in case of third overtone crystal usage have a common ground plane. Also connect the external components to the ground plain. To keep the noise coupled in via the PCB as small as possible, make loops and parasitics as small as possible. Choose smaller values of C_{x1} and C_{x2} if parasitics increase in the PCB layout.

Ensure that no high-speed or high-drive signals are near the RTCX1/2 signals.

13.5 Standard I/O pin configuration

Figure 46 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver enabled/disabled
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Digital input: Input buffer enabled/disabled
- Analog input

The default configuration for standard I/O pins is input buffer disabled and pull-up enabled. The weak MOS devices provide a drive capability equivalent to pull-up and pull-down resistors.

13.7 Suggested USB interface solutions

The USB device can be connected to the USB as bus-powered device (see Figure 48) or self-powered device (see Figure 49).

On the LPC43S50/S30/S20, USBn_VBUS pins are 5 V tolerant only when VDDIO is applied and at operating voltage level. Therefore, if the USBn_VBUS function is connected to the USB connector and the device is self-powered, the USBn_VBUS pins must be protected for situations when VDDIO = 0 V.

If VDDIO is always at operating level while VBUS = 5 V, the USBn_VBUS pin can be connected directly to the VBUS pin on the USB connector.

For systems where VDDIO can be 0 V and VBUS is directly applied to the USBn_VBUS pins, precautions must be taken to reduce the voltage to below 3.6 V, which is the maximum allowable voltage on the USBn_VBUS pins in this case.

One method is to use a voltage divider to connect the USBn_VBUS pins to VBUS on the USB connector. The voltage divider ratio should be such that the USB_VBUS pin will be greater than 0.7VDDIO to indicate a logic HIGH while below the 3.6 V allowable maximum voltage.

For the following operating conditions

$VBUS_{max}$ = 5.25 V

VDDIO = 3.6 V,

the voltage divider should provide a reduction of 3.6 V/5.25 V or ~0.686.

For bus-powered devices, a regulator powered by USB can provide 3.3 V to VDDIO whenever bus power is present and ensure that power to the USBn_VBUS pins is always present when the 5 V VBUS signal is applied. See Figure 48. If the VBUS function of the USB1 interface is not connected, configure the pin function for GPIO using the function control bits in the SYSCON block.

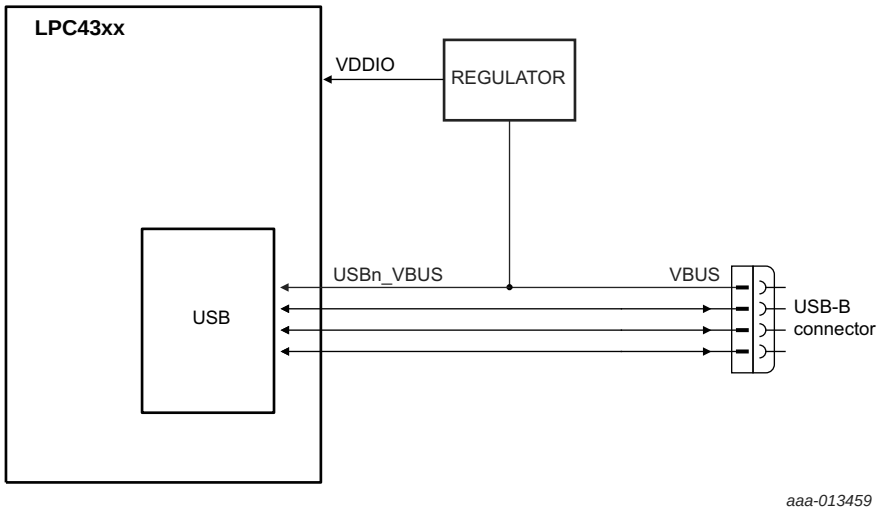
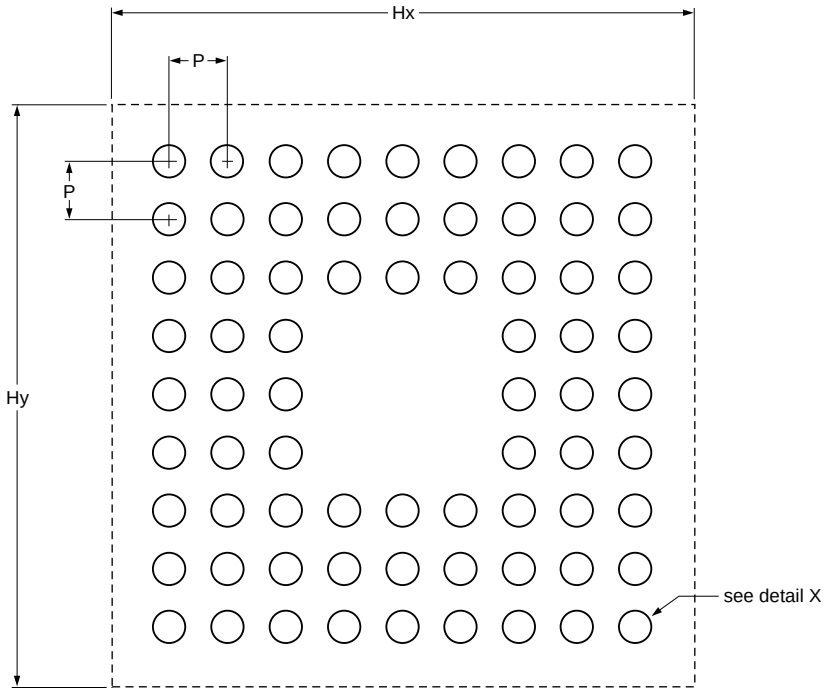


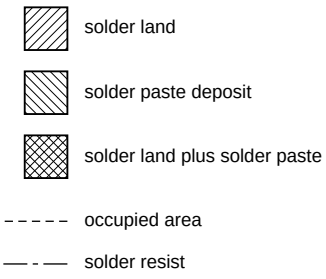
Fig 48. USB interface on a bus-powered device

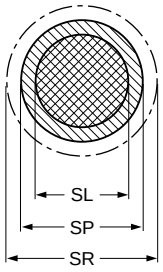
Footprint information for reflow soldering of TFBGA100 package **SOT926-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout





detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.80	0.330	0.400	0.480	9.400	9.400

sot926-1_fr

Fig 58. Reflow soldering of the TFBGA100 package